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ocket No.: LEE.068

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To the Director of the United States Patent and Trademark	Office: Please record the attached original documents or copy thereof.	
1. Name of conveying party(ies): LEE, Younggill KOH, Kwangwon LEE, Sangyun	Name and address of receiving party(ies): Name: Advanced Semiconductor Engineering, Inc. Address: 26 Chin 3rd Road,	
Additional names(s) of conveying party(ies)	Nantze Export Processing Zone	
3. Nature of conveyance:		
	11/	
☐ Security Agreement ☐ Change of Name	City: Kaoshiung State/Prov.:	
☐ Other	Country: Taiwan R.O.C. ZIP:	
Execution Date: December 16, 2005	Additional name(s) & address(es) □ Yes ☑ No	
 Application number(s) or patent numbers(s): If this document is being filed together with a new application Patent Application No. Filing date 	n, the execution date of the application is: B. Patent No.(s)	
NEW February 22, 2006 Additional numbers	s □ Yes ☒ No	
Name and address of party to whom correspondence concerning document should be mailed:	6. Total number of applications and patents involved:	
Name: Andrew J. Telesz, Jr.	7. Total fee (37 CFR 3.41):\$ 40.00	
Registration No. 33,581	☐ Enclosed - Any excess or insufficiency should be	
Address: Volentine Francos & Whitt, P.L.L.C.	credited or debited to deposit account	
11951 Freedom Drive, Suite 1260	Authorized to be charged to deposit account	
	8. Deposit account number:	
City: Reston State/Prov.: VA	50-0238 63/01/2006 LMUELLER 00000071 500238 11357952	
Country: U.S.A. ZIP: 20190	(Attach duplicate copy of this page if paying by deposit account)	
9. Statement and signature.	rmation is true and correct and any attached copy is a true copy February 22, 2006 Signature Date	

ASSIGNMENT

In consideration of the sum of One Dollar (\$1.00) and other good and valuable consideration paid to each of the undersigned

Insert
Name(s) of
Inventor(s)

1.	Yonggill LEE	5
2.	Kwangwon KOH	6.
3.	Sangyun LEE	7
4		O

Insert Name(s) of Assignee(s) &

the undersigned hereby sell(s) and assign(s) to

Advanced Semiconductor Engineering, Inc.

Address(es)

of 26 Chin 3rd Road, Nantze Export Processing Zone Kaoshiung, Taiwan R.O.C.

Title of

(hereinafter designated as the Assignee) the entire right, title and interest for the United States as defined in 35 USC 100, in the invention known as

PACKAGING METHOD FOR SEGREGATING DIE PADDLES OF A LEADFRAME

Invention
Date of
Signing of
Application

for which an application for patent in the United States of America has been executed by

the undersigned on December 16, 2005

The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuing. division or reissue thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such interference.

The undersigned agree(s) to execute all papers and documents and perform any act which may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the Assignee.

The undersigned hereby authorize(s) and request(s) the Commissioner of Patents to issue any and all Letters Patents of the United States resulting from said application or any division or divisions or continuing or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

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The undersigned hereby grant(s) to Adam C. Volentine, Reg. No. 33,289 and William S. Francos, Reg. No. 38,456, and the firm of VOLENTINE FRANCOS, P.L.L.C. the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent Office for recordation of this document.

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned

name(s).		
Date 2005.12	Signature of Inventor	YONGGILL LEE
		Yonggill LEE
Date 2005, 17	2.16 Signature of Inventor	
•		Kwangwon KOH
Date 2005 - 12	Signature of Inventor	SANG YUN LEE
	.*	Sangyun LEE
Date	Signature of Inventor	
Date	Signature of Inventor	
Date	Signature of Inventor	
<u> </u>		•
		
Date	Signature of Inventor	
		•
Date	Signature of Inventor	
witnessed by Patent and T	y at least two witnesses who sign here	that the execution by the Inventor(s) be . However, the current practice of the U.S. gnment even it has not been witnessed.)
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